

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type  $\overline{\text{T}}$ -MOSIV

## 2SK3763

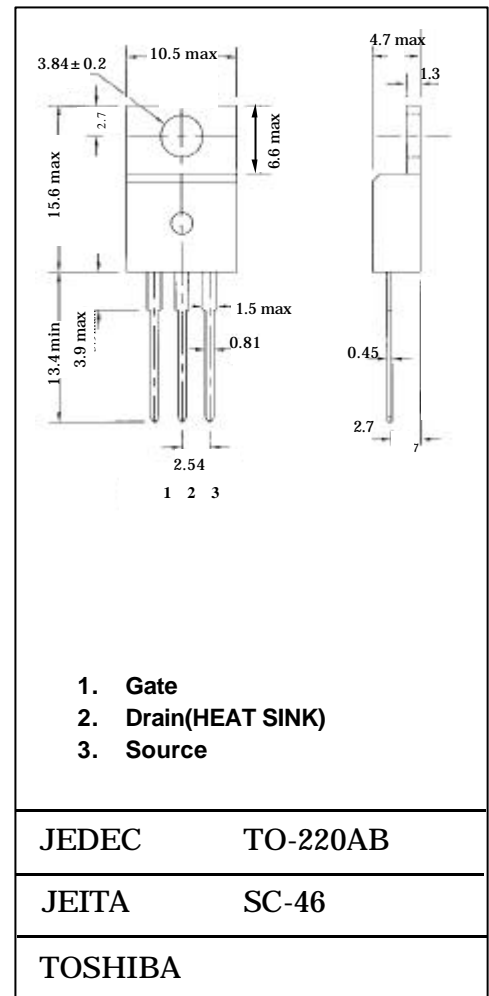
unit : mm

### Switching Regulator Applications

- Low drain-source ON resistance:  $R_{DS(ON)} = 3.7$  (typ.)
- High forward transfer admittance:  $|Y_{fs}| = 2.6$  S (typ.)
- Low leakage current:  $I_{DSS} = 100$   $\mu$ A ( $V_{DS} = 720$  V)
- Enhancement-mode:  $V_{th} = 2.0 \sim 4.0$  V ( $V_{DS} = 10$  V,  $I_D = 1$  mA)

### Maximum Ratings ( $T_a = 25^\circ\text{C}$ )

Characteristics		Symbol	Rating	Unit
Drain-source voltage		$V_{DSS}$	900	V
Drain-gate voltage ( $R_{GS} = 20$ k $\Omega$ )		$V_{DGR}$	900	V
Gate-source voltage		$V_{GSS}$	$\pm 30$	V
Drain current	DC (Note 1)	$I_D$	3	A
	Pulse ( $t = 1$ ms) (Note 1)	$I_{DP}$	9	
Drain power dissipation ( $T_c = 25^\circ\text{C}$ )		$P_D$	69	W
Single pulse avalanche energy (Note 2)		$E_{AS}$	56.7	mJ
Avalanche current		$I_{AR}$	3	A
Repetitive avalanche energy (Note 3)		$E_{AR}$	6.9	mJ
Channel temperature		$T_{ch}$	150	$^\circ\text{C}$
Storage temperature range		$T_{stg}$	-55~150	$^\circ\text{C}$



Weight : 2.0g(typ.)

### Thermal Characteristics

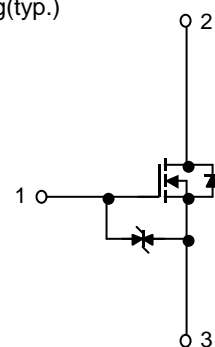
Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	$R_{th(ch-c)}$	1.81	$^\circ\text{C/W}$
Thermal resistance, channel to ambient	$R_{th(ch-a)}$	83.3	$^\circ\text{C/W}$

Note 1: Please use devices on conditions that the channel temperature is below  $150^\circ\text{C}$ .

Note 2:  $V_{DD} = 90$  V,  $T_{ch} = 25^\circ\text{C}$ ,  $L = 11.6$  mH,  $I_{AR} = 3.0$  A,  $R_G = 25$   $\Omega$

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device. Please handle with caution.



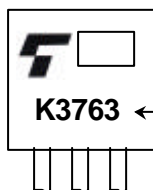
## Electrical Characteristics (Ta = 25°C)

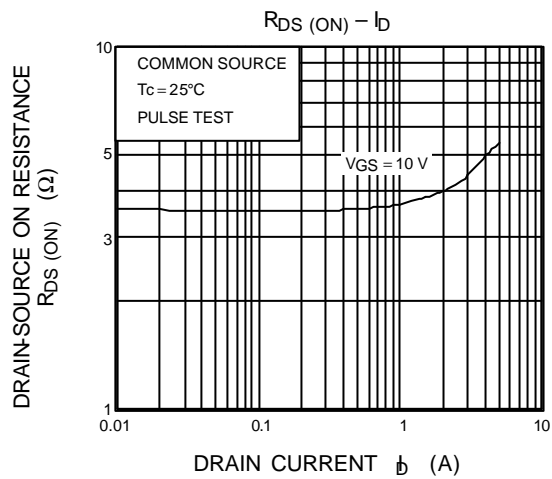
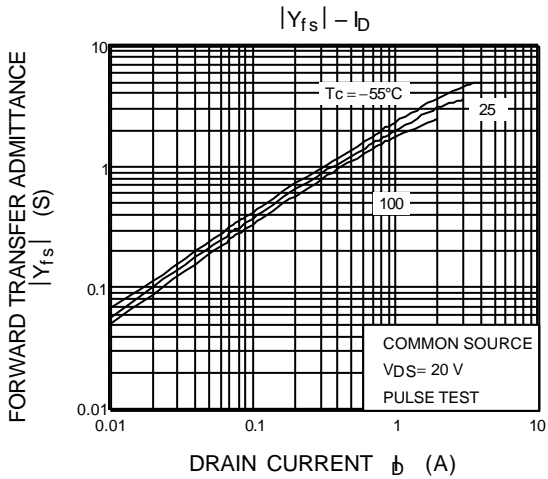
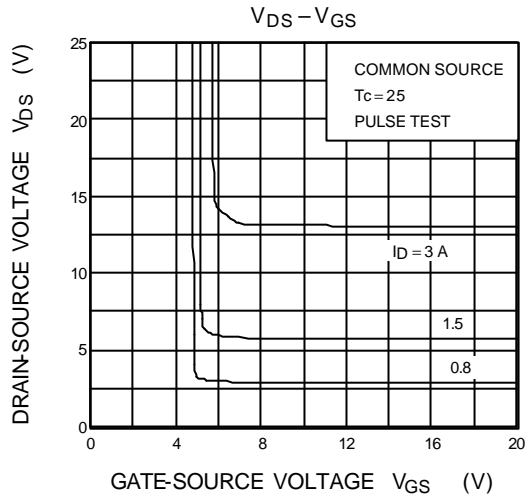
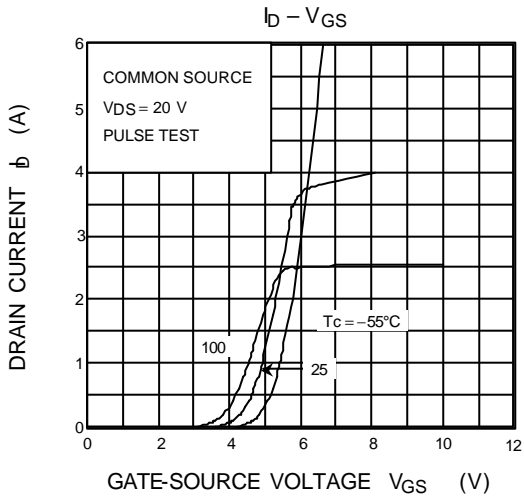
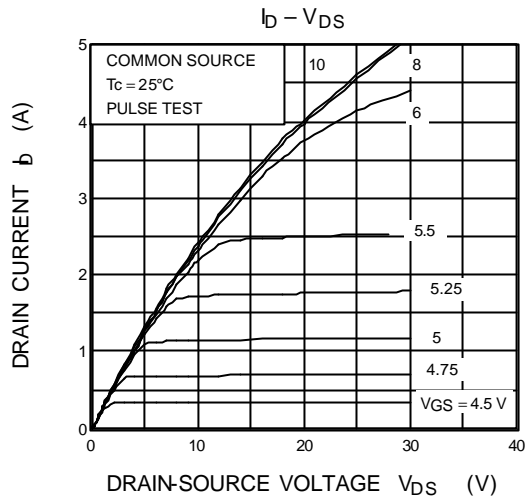
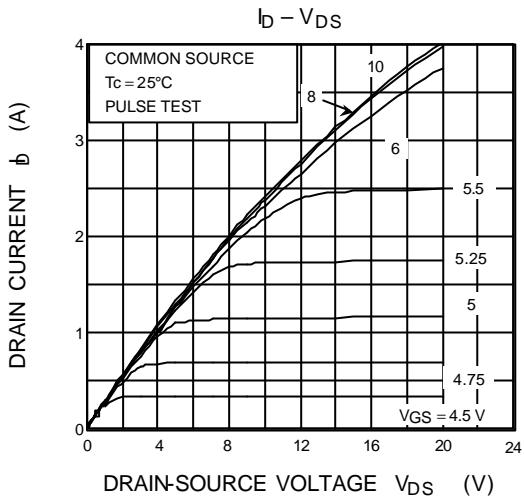
Characteristics		Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current		$I_{GSS}$	$V_{GS} = \pm 30\text{ V}, V_{DS} = 0\text{ V}$	—	—	$\pm 10$	$\mu\text{A}$
Gate-source breakdown voltage		$V_{(BR)GSS}$	$I_G = \pm 10\ \mu\text{A}, V_{GS} = 0\text{ V}$	$\pm 30$	—	—	V
Drain cut-off current		$I_{DSS}$	$V_{DS} = 720\text{ V}, V_{GS} = 0\text{ V}$	—	—	100	$\mu\text{A}$
Drain-source breakdown voltage		$V_{(BR)DSS}$	$I_D = 10\text{ mA}, V_{GS} = 0\text{ V}$	900	—	—	V
Gate threshold voltage		$V_{th}$	$V_{DS} = 10\text{ V}, I_D = 1\text{ mA}$	2.0	—	4.0	V
Drain-source ON resistance		$R_{DS(ON)}$	$V_{GS} = 10\text{ V}, I_D = 1.5\text{ A}$	—	3.7	4.3	$\Omega$
Forward transfer admittance		$ Y_{fs} $	$V_{DS} = 20\text{ V}, I_D = 1.5\text{ A}$	0.65	2.6	—	S
Input capacitance		$C_{iss}$	$V_{DS} = 25\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	—	700	—	pF
Reverse transfer capacitance		$C_{rss}$		—	15	—	
Output capacitance		$C_{oss}$		—	75	—	
Switching time	Rise time	$t_r$		—	20	—	ns
	Turn-on time	$t_{on}$		—	60	—	
	Fall time	$t_f$		—	35	—	
	Turn-off time	$t_{off}$		Duty $\leq 1\%$ , $t_w = 10\ \mu\text{s}$	—	125	
Total gate charge		$Q_g$	$V_{DD} = 400\text{ V}, V_{GS} = 10\text{ V}, I_D = 3\text{ A}$	—	17	—	nC
Gate-source charge		$Q_{gs}$		—	10	—	
Gate-drain charge		$Q_{gd}$		—	7	—	

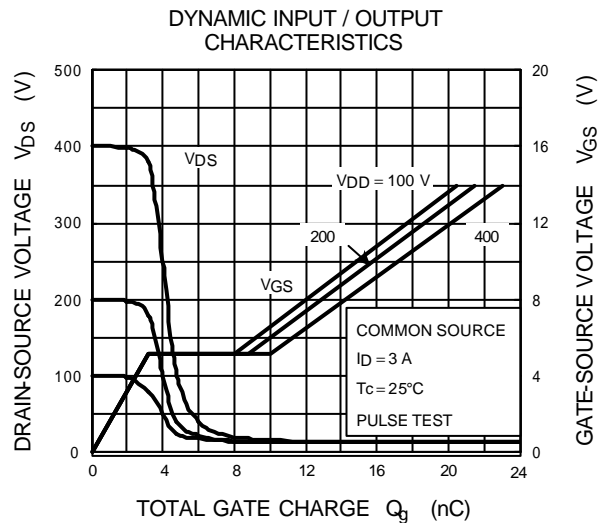
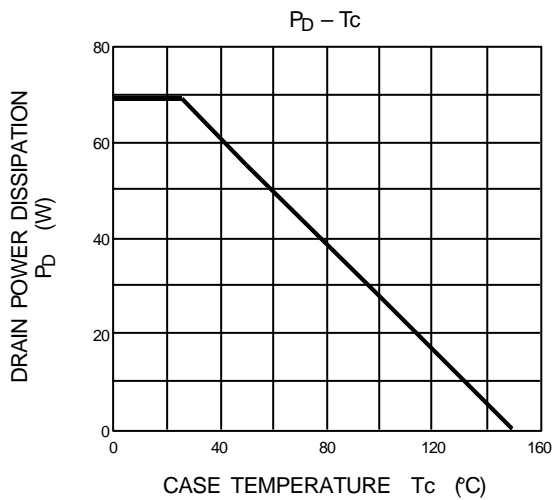
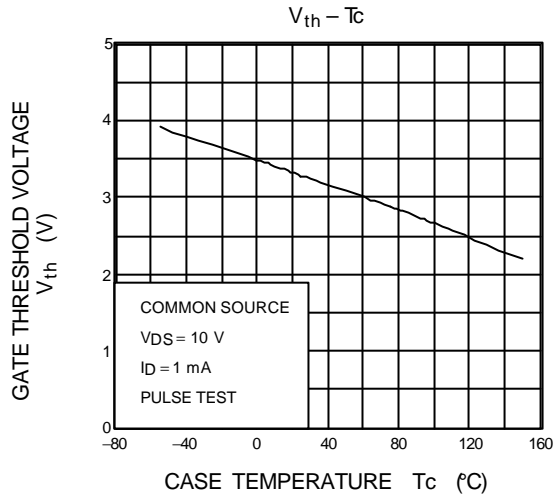
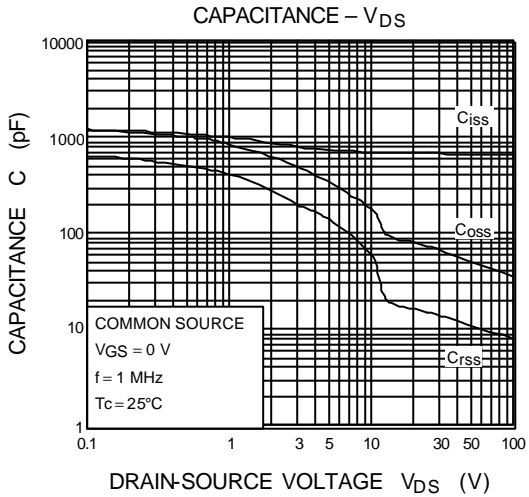
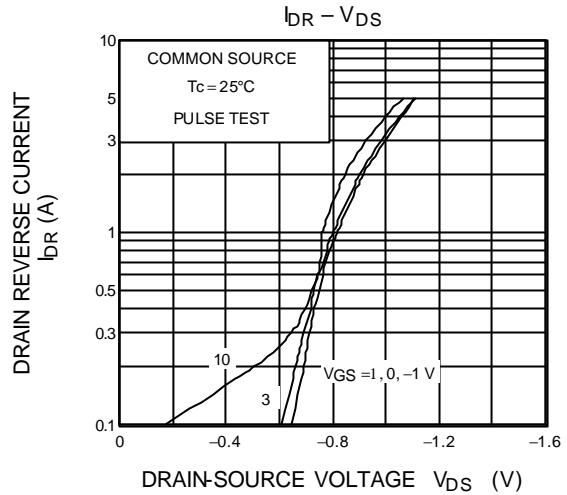
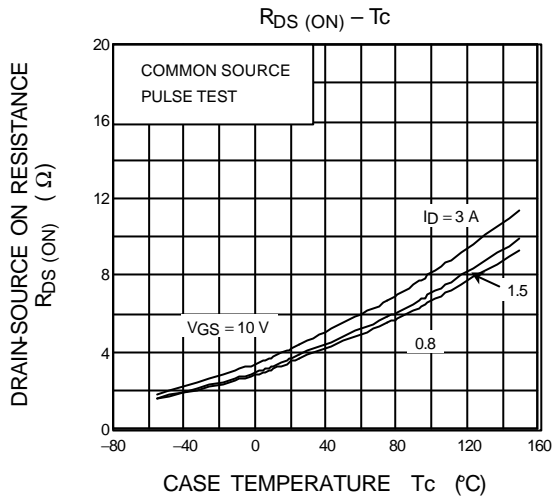
## Source-Drain Ratings and Characteristics (Ta = 25°C)

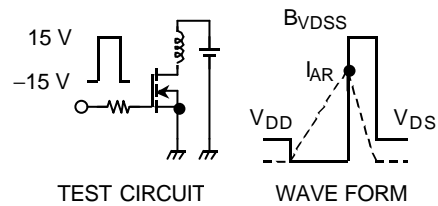
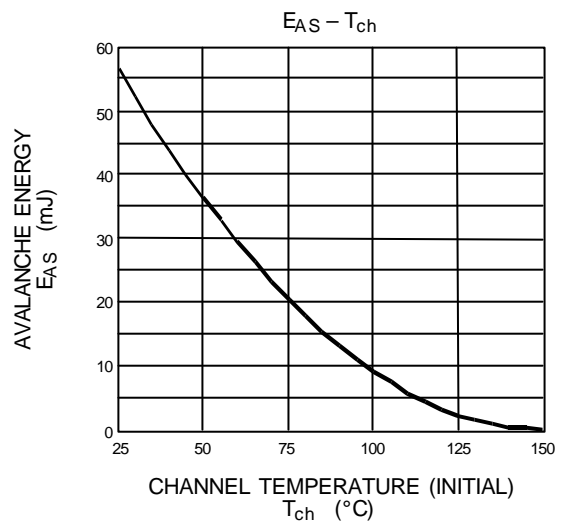
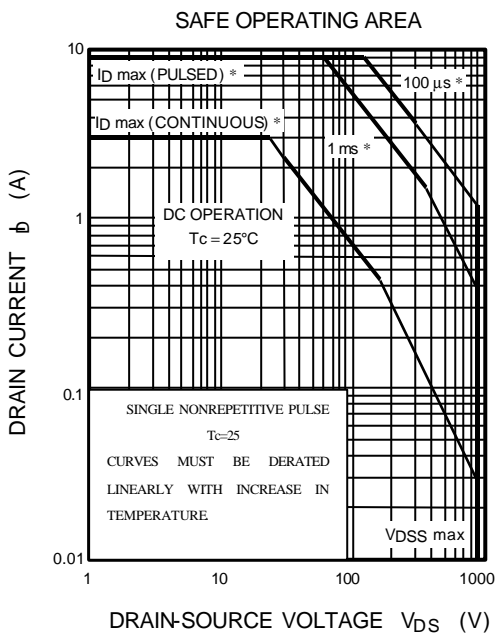
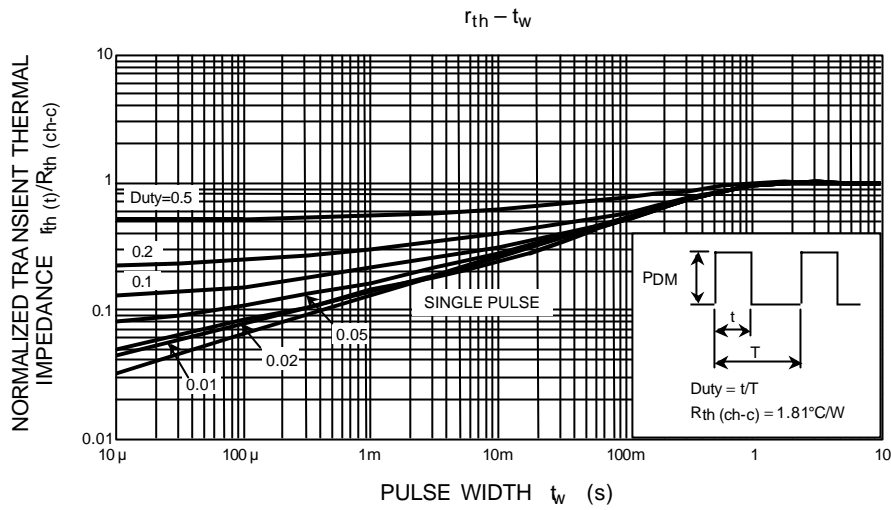
Characteristics		Symbol	Test Condition	Min	Typ.	Max	Unit
Continuous drain reverse current (Note 1)		$I_{DR}$	—	—	—	3	A
Pulse drain reverse current (Note 1)		$I_{DRP}$	—	—	—	9	A
Forward voltage (diode)		$V_{DSF}$	$I_{DR} = 3\text{ A}, V_{GS} = 0\text{ V}$	—	—	-1.9	V
Reverse recovery time		$t_{rr}$	$I_{DR} = 3\text{ A}, V_{GS} = 0\text{ V}$ ,	—	850	—	ns
Reverse recovery charge		$Q_{rr}$	$dI_{DR}/dt = 100\text{ A}/\mu\text{s}$	—	4.7	—	$\mu\text{C}$

## Marking









$R_G = 25 \Omega$   
 $V_{DD} = 90 \text{ V}, L = 11.6 \text{ mH}$

$$\dot{A}_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left( \frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right)$$

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